



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

* : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-08-03
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Flavio Di Francesco	Representative Title	AMS Material Declaration Champions
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KD6P*1021AB6	A	BO2A	2015-08-03
	Amount	UoM	Unit type	ST ECOPACK Grade
	34.89	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3,4,4,1,0	8	gull wing	
Comment	Package: TSSOP 8 BODY 4.4 PITCH 0.65; MD valid for TSC1021BIPT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KD6P*1021AB6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	1.548	mg	supplier	die	Silicon (Si)	7440-21-3		1.461	mg	943798	41880
				supplier	metallization	Aluminium (Al)	7429-90-5		0.015	mg	9690	430
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1292	57
				supplier	Passivation	Silicon Nitride	12033-89-5		0.004	mg	2584	115
				supplier	Passivation	Silicon Oxide	7631-86-9		0.025	mg	16150	717
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.025	mg	16150	717
Leadframe	Copper & its alloys	14.679	mg	supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.016	mg	10336	459
				supplier	alloy	Copper (Cu)	7440-50-8		13.981	mg	952449	400774
				supplier	alloy	Nickel (Ni)	7440-02-0		0.436	mg	29702	12498
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.022	mg	1499	631
				supplier	alloy	Silicon (Si)	7440-21-3		0.094	mg	6404	2695
				supplier	metallization	Nickel (Ni)	7440-02-0		0.133	mg	9061	3813
Die attach	Other inorganic materials	0.563	mg	supplier	metallization	Palladium (Pd)	7440-05-3		0.009	mg	613	258
				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	272	115
				supplier	glue or tape (choose)	Silver (Ag)	7440-22-4		0.512	mg	909414	14677
				supplier	glue or tape	acrylate	Proprietary		0.028	mg	49734	803
				supplier	glue or tape	Methacrylate	Proprietary		0.023	mg	40853	659
				supplier	wire	Copper (Cu)	7440-50-8		0.023	mg	1000000	659
Encapsulation	Other Organic Materials	18.072	mg	supplier	mold compound	Silica, vitreous	60676-86-0		15.850	mg	877047	454350
				supplier	mold compound	Epoxy resin	85954-11-6		0.722	mg	39951	20697
				supplier	mold compound	Epoxy	29690-82-2		0.722	mg	39951	20697
				supplier	mold compound	phenol resin	Proprietary		0.543	mg	30046	15565
				supplier	mold compound	additive	Proprietary		0.181	mg	10015	5188
				supplier	mold compound	carbon black	1333-86-4		0.054	mg	2988	1548